

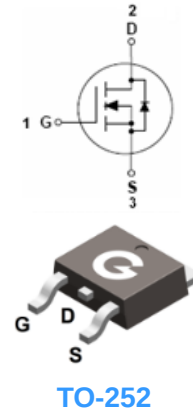
Features

- Low power loss by high speed switching and low on-resistance
- Excellent thermal behavior
- Product validation acc. JEDEC Standard
- RoHS compliant with Halogen-free

HF

Mechanical Data

- Case: TO-252
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
SJM60R600XD	TO-252	80 pcs / Tube & 2500 pcs / Tape & Reel	SJM60R600XD

Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DS}	600	V
Gate-to-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ($T_C = 25^\circ\text{C}$)	I_D	8	A
Continuous Drain Current ($T_C = 100^\circ\text{C}$)		5	A
Pulsed Drain Current ($t_p = 10\mu\text{s}$, $T_C = 25^\circ\text{C}$)	I_{DM}	32	A
Single Pulse Avalanche Energy ^{*3}	E_{AS}	200	mJ
Power Dissipation ($T_C = 25^\circ\text{C}$)	P_D	63	W
Operating Junction Temperature Range	T_J	$-55 \sim +150$	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	$-55 \sim +150$	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	-	2	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Air ^{*1}	$R_{\theta JA}$	-	-	62	$^\circ\text{C/W}$

Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	600	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 600V, V _{GS} = 0V	-	-	1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±30V, V _{DS} = 0V	-	-	±100	nA
On Characteristics						
R _{DS(ON)}	Drain-Source On-resistance *2	V _{GS} = 10V, I _D = 4A	-	0.45	0.6	Ω
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.5	3.3	4.5	V
R _G	Gate Resistance	V _{GS} = 0V, f = 1MHz	-	12	-	Ω
Dynamic Characteristics						
C _{ISS}	Input Capacitance	V _{GS} = 0V	-	408	-	pF
C _{OSS}	Output Capacitance	V _{DS} = 40V	-	88	-	
C _{RSS}	Reverse Transfer Capacitance	f = 250kHz	-	6.5	-	
Switching Characteristics						
t _{d(ON)}	Turn-on Delay Time	V _{DD} = 480V V _{GS} = 15V I _D = 4A R _G = 3.3Ω	-	25	-	ns
t _r	Turn-on Rise Time		-	33	-	
t _{d(OFF)}	Turn-Off Delay Time		-	40	-	
t _f	Turn-Off Fall Time		-	66	-	
Q _G	Total Gate-Charge	V _{DD} = 480V V _{GS} = 10V I _D = 4A	-	16.4	-	nC
Q _{GS}	Gate to Source Charge		-	2.3	-	
Q _{GD}	Gate to Drain (Miller) Charge		-	9.2	-	
Source-Drain Diode Characteristics						
V _{SD}	Diode Forward Voltage *2	I _{SD} = 4A, V _{GS} = 0V	-	0.82	1.2	V
t _{rr}	Reverse Recovery Time	I _F = 4A, V _R = 400V	-	230	-	ns
Q _{rr}	Reverse Recovery Charge	di/dt = 100A/μs	-	1.7	-	μC

Notes:

- The data tested by surface mounted on a minimum recommended FR-4 board
- The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- The E_{AS} data shows Max. rating. The test condition is $V_{DD} = 100V, V_{GS} = 15V, L = 50mH$

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

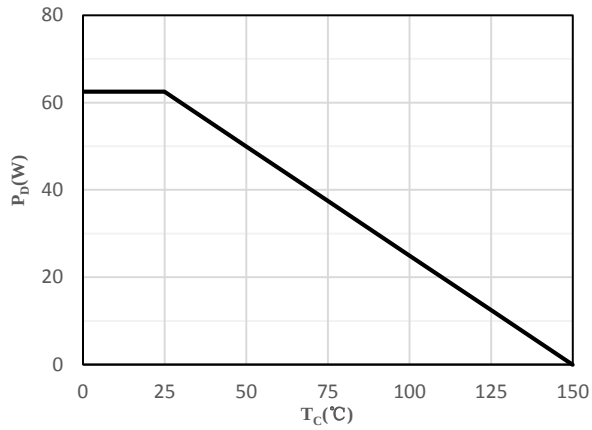


Fig 1 Power Dissipation

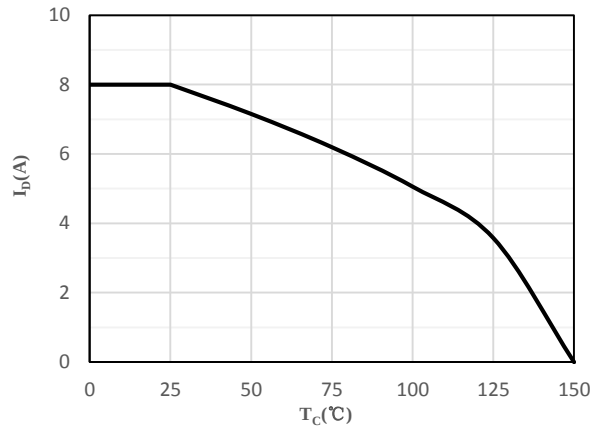


Fig 2 Drain Current

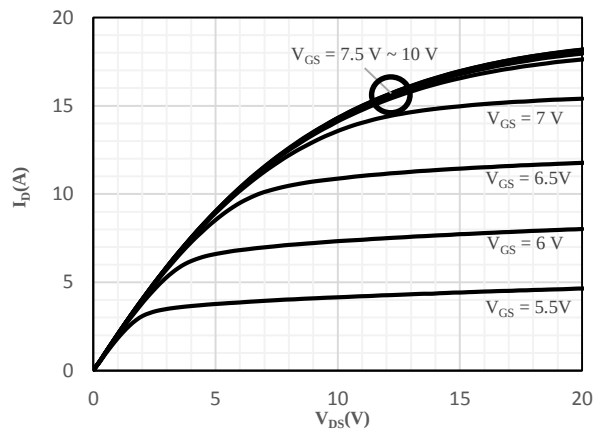


Fig 3 Typical Output Characteristics

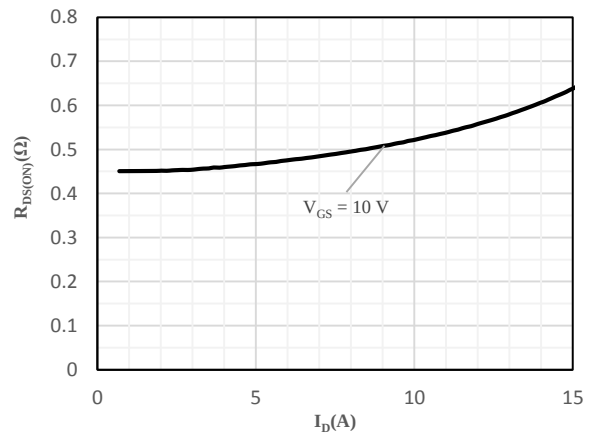


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

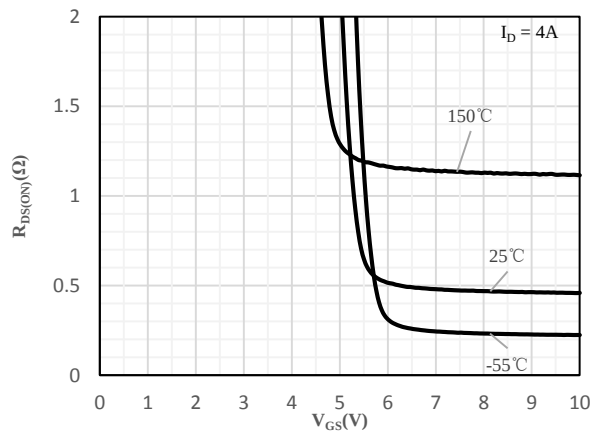


Fig 5 On-Resistance vs. Gate-Source Voltage

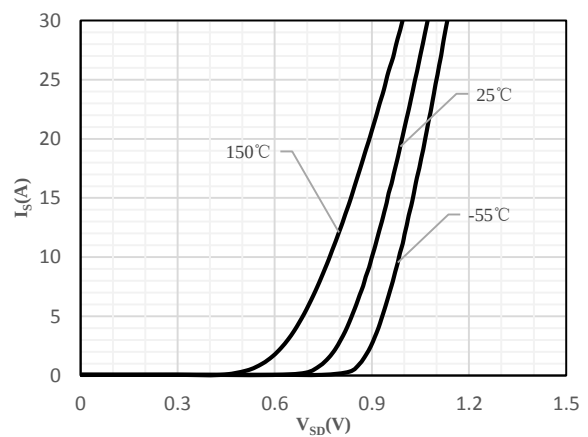


Fig 6 Body-Diode Characteristics

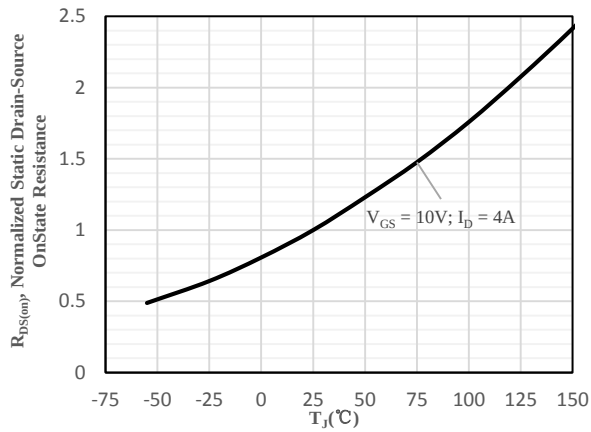


Fig 7 Normalized On-Resistance vs. Junction Temperature

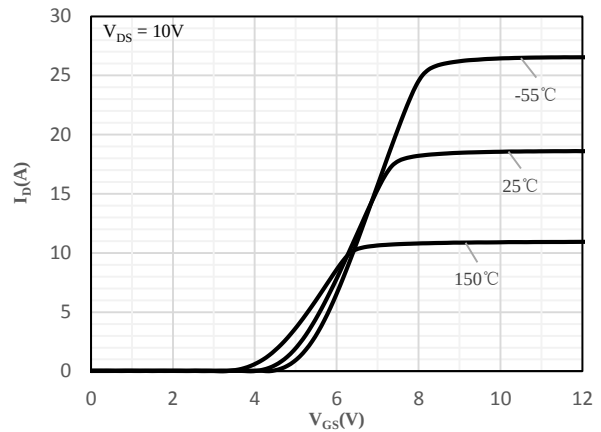


Fig 8 Transfer Characteristics

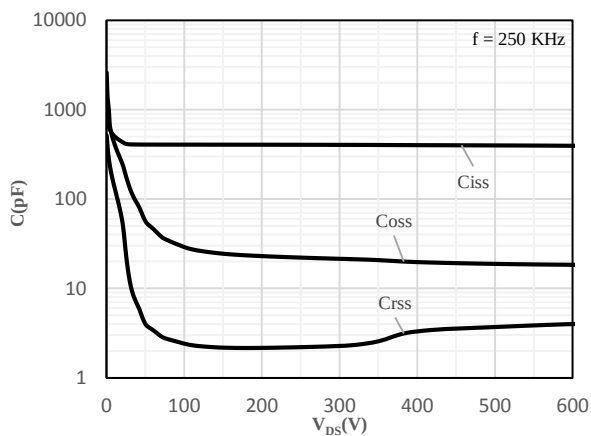


Fig 9 Capacitance Characteristics

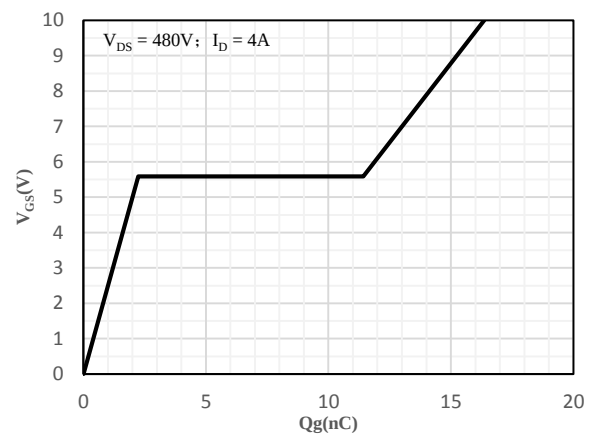


Fig 10 Gate-Charge Characteristics

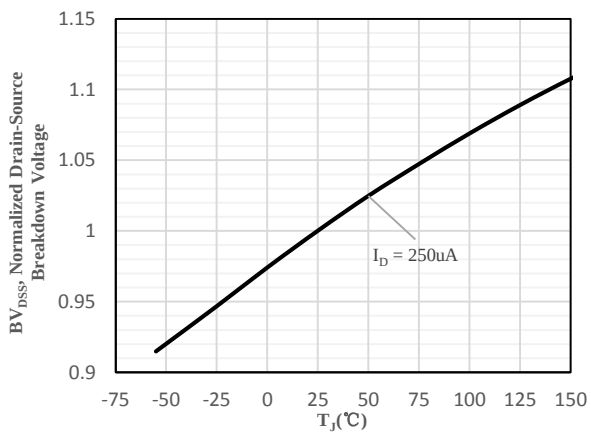


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

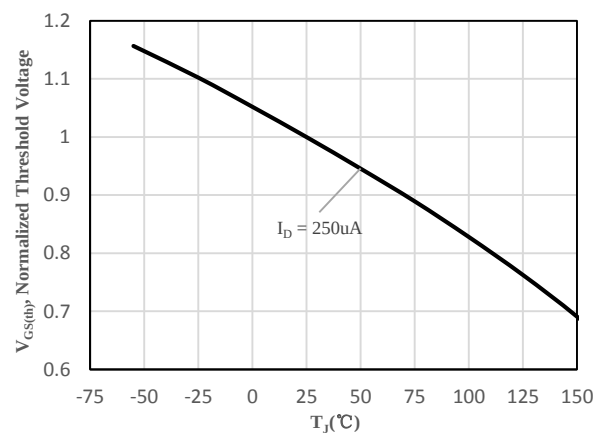


Fig 12 Normalized $V_{GS(th)}$ vs. Junction Temperature

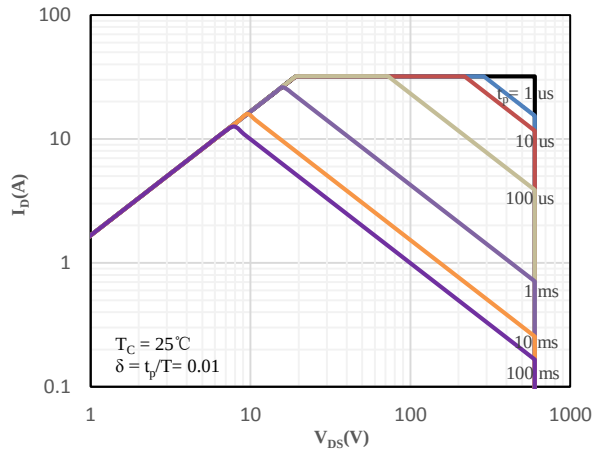


Fig 13 Safe Operation Area

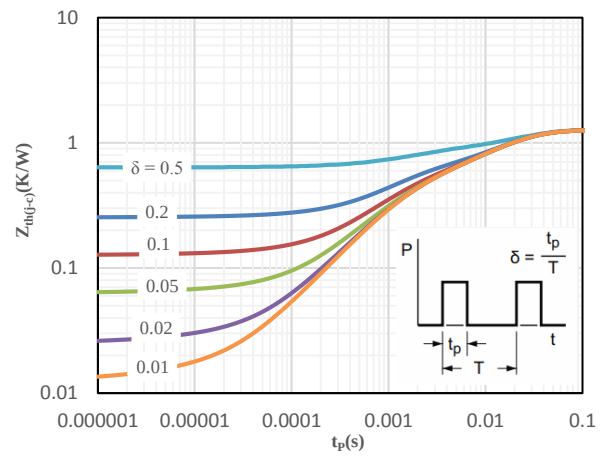
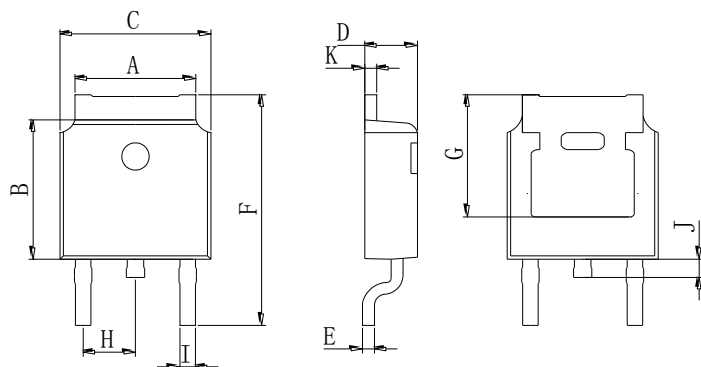


Fig 14 Maximum transient thermal impedance

Package Outline Dimensions (Unit: mm)



TO-252		
Dimension	Min.	Max.
A	5.05	5.65
B	5.80	6.40
C	6.25	6.85
D	2.20	2.40
E	0.40	0.60
F	9.71	10.31
G	5.05	5.65
H	2.10	2.50
I	0.70	0.90
J	0.50	0.70
K	0.40	0.60

Mounting Pad Layout (Unit: mm)

TO-252

